

# **MD1820**

# High-Speed 4-Channel MOSFET Driver with Non-Inverting Outputs

#### Features

- Non-inverting, 4-channel MOSFET Driver
- · 6 ns Rise and Fall Time
- 2A Peak Output Source and Sink Currents
- 1.8V to 5V Input CMOS Compatible
- 5V to 10V Total Supply Voltage
- · Smart Logic Threshold
- Low-jitter Design
- Four Matched Channels
- Drives Two P-channel and Two N-channel MOSFETs
- · Outputs can Swing below Ground
- Low-inductance Quad Flat No-lead Package
- · High-performance, Thermally Enhanced Package

#### Applications

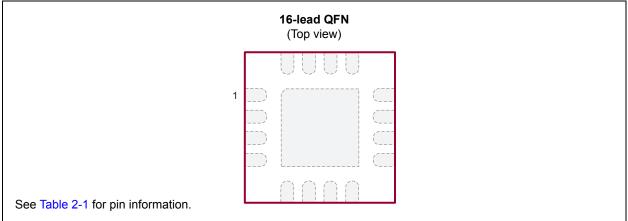
- Medical Ultrasound Imaging
- Piezoelectric Transducer Drivers
- Non-destructive Testing (NDT)
- · PIN Diode Driver
- CCD Clock Driver/buffer
- · High-speed Level Translator

#### **General Description**

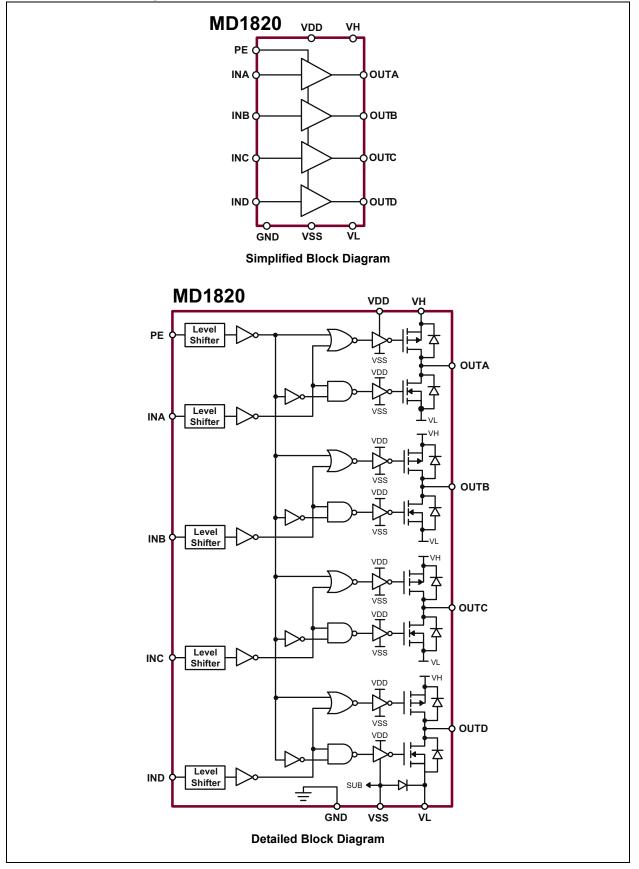
The MD1820 is a high-speed, 4-channel MOSFET driver designed to drive high-voltage P-channel and N-channel MOSFETs for medical ultrasound applications and other applications requiring a high output current for a capacitive load. The high-speed input stage of the MD1820 can operate from a 1.8V to 5V logic interface with an optimum operating input signal range of 1.8V to 3.3V. An adaptive threshold circuit is used to set the level translator switch threshold to the average of the input logic 0 and logic 1 levels. The input logic levels may be ground referenced, even though the driver is putting out bipolar signals. The level translator uses a proprietary circuit, which provides DC coupling together with high-speed operation.

The output stage of the MD1820 has separate power connections, enabling the output signal L and H levels to be chosen independently from the supply voltages used for the majority of the circuit. As an example, the input logic levels may be 0V and 1.8V, the control logic may be powered by +5V and -5V and the output L and H levels may be varied anywhere over the range of -5V to +5V. The output stage is capable of peak currents of up to ±2A, depending on the supply voltages used and load capacitance present. The PE pin serves a dual purpose. First, its logic H level is used to compute the threshold voltage level for the channel input level translators. Second, when PE is low, the outputs are High Z. This assists in properly precharging the AC coupling capacitors that may be used in series in the gate drive circuit of an external PMOS and NMOS transistor pair.

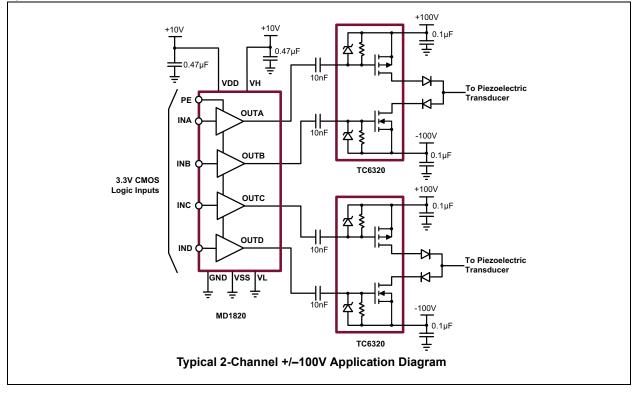
#### Package Type

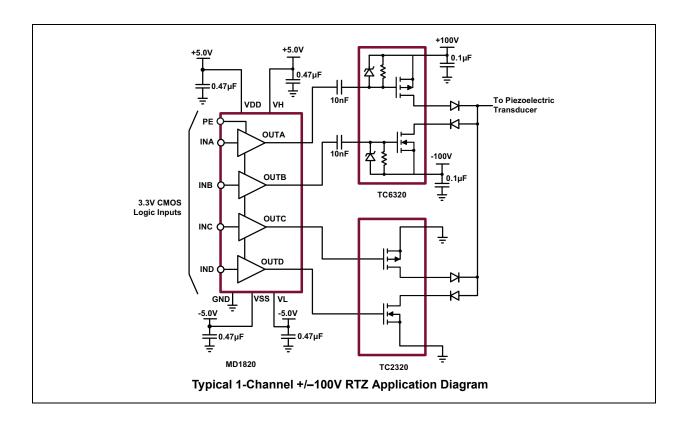


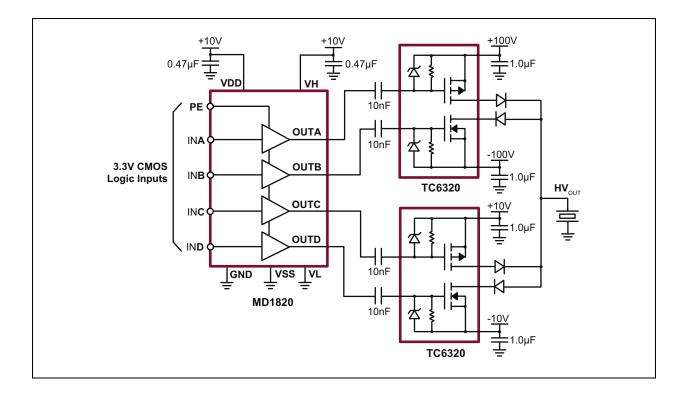
#### **Functional Block Diagrams**



#### **Typical Application Circuits**







# 1.0 ELECTRICAL CHARACTERISTICS

#### Absolute Maximum Ratings†

| Logic Supply Voltage, $V_{DD}$ - $V_{SS}$<br>Output High Supply Voltage, $V_H$<br>Output Low Supply Voltage, $V_L$<br>Low-side Supply Voltage, $V_{SS}$<br>Logic Input Levels<br>Maximum Junction Temperature, $T_J$ | $\label{eq:VL} \begin{array}{c} V_L 0.5 \mbox{V to } V_{DD} \mbox{+}0.5 \mbox{V} \\ V_{SS} 0.5 \mbox{V to } V_{H} \mbox{+}0.5 \mbox{V} \\ 6 \mbox{V to } \mbox{+}0.5 \mbox{V} \\ 0.5 \mbox{V to } \mbox{GND} \mbox{+}5.5 \mbox{V} \\ \mbox{+}125^{\circ} \mbox{C} \end{array}$ |
|--|--|
| Operating Ambient Temperature, T <sub>A</sub><br>Storage Temperature, T <sub>S</sub>   |  |
| Package Power Dissipation:<br>16-lead QFN  | 2 2W   |
| ESD Rating (Note 1)  |  |

**† Notice:** Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

**Note 1:** Device is ESD sensitive. Handling precautions are recommended.

### DC ELECTRICAL CHARACTERISTICS

| Electrical Specifications: $V_H = V_{DD} = 10V$ , $V_L = V_{SS} = GND = 0V$ , $V_{PE} = 3.3V$ , $T_A = 25^{\circ}C$ |                     |                      |      |                    |      |                                    |  |  |  |  |  |
|---|---------------------|----------------------|------|--------------------|------|------------------------------------|--|--|--|--|--|
| Parameter   | Sym.                | Min.                 | Тур. | Max.               | Unit | Conditions                         |  |  |  |  |  |
| Logic Supply Voltage  | $V_{DD}-V_{SS}$     | 4.75                 | _    | 11.5               | V    | $4V \le V_{DD} \le 11.5V$          |  |  |  |  |  |
| Low-side Supply Voltage   | V <sub>SS</sub>     | -5.5                 | _    | 0                  | V    |                                    |  |  |  |  |  |
| Output High Supply Voltage  | V <sub>H</sub>      | V <sub>SS</sub> +2   |      | V <sub>DD</sub>    | V    |                                    |  |  |  |  |  |
| Output Low Supply Voltage   | $V_L$               | V <sub>SS</sub>      |      | V <sub>DD</sub> –4 | V    |                                    |  |  |  |  |  |
| V <sub>DD</sub> Quiescent Current   | I <sub>DDQ</sub>    | —                    | 60   |                    | μA   | No input transitions, PE = 0       |  |  |  |  |  |
| V <sub>H</sub> Quiescent Current  | I <sub>HQ</sub>     | —                    | 2    | —                  | μA   | No input transitions, $PE = 0$     |  |  |  |  |  |
| V <sub>DD</sub> Quiescent Current   | I <sub>DDQ</sub>    | —                    | 0.8  | _                  | mA   | No input transitions, PE = 1       |  |  |  |  |  |
| V <sub>H</sub> Quiescent Current  | I <sub>HQ</sub>     | —                    | 2    | _                  | μA   |                                    |  |  |  |  |  |
| V <sub>DD</sub> Average Current   | I <sub>DD</sub>     | —                    | 3.5  | —                  | mA   | One channel on at 5 MHz, no load   |  |  |  |  |  |
| V <sub>H</sub> Average Current  | Ι <sub>Η</sub>      | —                    | 10   | _                  | mA   | One channel on at 5 MHz, no load   |  |  |  |  |  |
| Input Logic Voltage High  | V <sub>IH</sub>     | V <sub>PE</sub> -0.3 | _    | V <sub>PE</sub>    | V    |                                    |  |  |  |  |  |
| Input Logic Voltage Low   | V <sub>IL</sub>     | 0                    | —    | 0.3                | V    | For logic inputs INA, INB, INC and |  |  |  |  |  |
| Input Logic Current High  | I <sub>IH</sub>     | —                    | _    | 1                  | μA   | IND                                |  |  |  |  |  |
| Input Logic Current Low   | ١ <sub>IL</sub>     | —                    | _    | 1                  | μA   |                                    |  |  |  |  |  |
| PE Input logic Voltage High   | V <sub>IH</sub>     | 1.7                  | 3.3  | 5.25               | V    |                                    |  |  |  |  |  |
| PE Input Logic Voltage Low  | V <sub>IL</sub>     | 0                    |      | 0.3                | V    | For logic input PE                 |  |  |  |  |  |
| PE Input Resistance   | R <sub>IN_PE</sub>  | 100                  | _    | —                  | kΩ   |                                    |  |  |  |  |  |
| Logic Input Capacitance   | C <sub>IN</sub>     | _                    | 5    | 10                 | pF   |                                    |  |  |  |  |  |
| Output Sink Resistance  | R <sub>SINK</sub>   | —                    | 1.5  | _                  | Ω    | I <sub>SINK</sub> = 50 mA          |  |  |  |  |  |
| Output Source Resistance  | R <sub>SOURCE</sub> |                      | 2    | _                  | Ω    | I <sub>SOURCE</sub> = 50 mA        |  |  |  |  |  |
| Peak Output Sink Current  | I <sub>SINK</sub>   | _                    | 2    |                    | Α    |                                    |  |  |  |  |  |
| Peak Output Source Current  | ISOURCE             | —                    | 2    |                    | Α    |                                    |  |  |  |  |  |

# AC ELECTRICAL CHARACTERISTICS

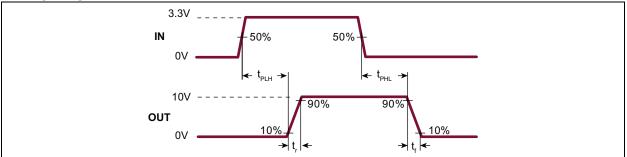
| Electrical Specifications: $V_H = V_{DD} = 10V$ , $V_L = V_{SS} = GND = 0V$ , $V_{PE} = 3.3V$ , $T_A = 25^{\circ}C$ |  |           |     |           |    |   |  |  |  |  |
|---|--|-----------|-----|-----------|----|---|--|--|--|--|
| Parameter   | Sym.                                   | Sym. Min. |     | Тур. Мах. |    | Conditions  |  |  |  |  |
| Input or PE Rise and Fall Time  | t <sub>irf</sub>                       |           |     | 10        | ns | Logic input edge speed<br>requirement   |  |  |  |  |
| Propagation Delay when Output is from Low to High   | t <sub>PLH</sub>                       | _         | 6.5 | _         | ns |   |  |  |  |  |
| Propagation Delay when Output is from High to Low   | t <sub>PHL</sub>                       | _         | 6.5 | _         | ns | C <sub>LOAD</sub> = 1000 pF (See <b>Timing</b><br><b>Diagram</b> .), input signal rise/fall |  |  |  |  |
| Output Rise Time  | t <sub>r</sub>                         | _         | 7   | _         | ns | time 2 ns   |  |  |  |  |
| Output Fall Time  | t <sub>f</sub>                         | —         | 7   | _         | ns |   |  |  |  |  |
| Rise and Fall Time Matching   | l t <sub>r</sub> t <sub>f</sub> l      | —         | 1   | _         | ns |   |  |  |  |  |
| Propagation Low to High and High to Low Matching  | I t <sub>PLH</sub> –t <sub>PHL</sub> I | _         | 1   | _         | ns | For each channel  |  |  |  |  |
| Propagation Delay Matching  | $\Delta t_{dm}$                        | _         | ±2  | _         | ns | Device-to-device delay match  |  |  |  |  |
| PE On Time  | t <sub>PE-ON</sub>                     | _         | _   | 5         | μs | V <sub>PE</sub> = 1.7V~5.25V,   |  |  |  |  |
| PE Off-time   | t <sub>PE-OFF</sub>                    | _         | _   | 4         | μs | V <sub>DD</sub> = 7.5V~11.5V,<br>–20°C~85°C   |  |  |  |  |

# **TEMPERATURE SPECIFICATIONS**

| Sym.                       | Min.   | Тур.   | Max.   | Unit  | Conditions  |  |  |  |  |
|----------------------------|--|--|--|---|---|--|--|--|--|
| TEMPERATURE RANGE          |  |  |  |   |   |  |  |  |  |
| TJ                         | —  | _  | +125   | °C  |   |  |  |  |  |
| T <sub>A</sub>             | -20  | —  | +85  | °C  |   |  |  |  |  |
| Τ <sub>S</sub>             | -65  | _  | +150   | °C  |   |  |  |  |  |
| PACKAGE THERMAL RESISTANCE |  |  |  |   |   |  |  |  |  |
| $\theta_{JA}$              | _  | 55   | _  | °C/W  | Note 1  |  |  |  |  |
|                            | T <sub>J</sub><br>T <sub>A</sub><br>T <sub>S</sub> | $\begin{array}{c c} T_{J} & - \\ T_{A} & -20 \\ T_{S} & -65 \\ \hline \end{array}$ | $ \begin{array}{c ccccccccccccccccccccccccccccccccccc$ | $\begin{array}{c ccccccccccccccccccccccccccccccccccc$ | $\begin{array}{c ccccccccccccccccccccccccccccccccccc$ |  |  |  |  |

Note 1: 1 oz four-layer 3" x 4" PCB

## **Timing Diagram**



#### TABLE 1-1:TRUTH FUNCTION TABLE

| Logic | Logic Inputs |                |  |  |  |
|-------|--------------|----------------|--|--|--|
| PE    | IN           | Output         |  |  |  |
| Н     | L            | VL             |  |  |  |
| Н     | Н            | V <sub>H</sub> |  |  |  |
| L     | Х            | High Z         |  |  |  |

#### 2.0 PIN DESCRIPTION

The details on the pins of MD1820 are listed on Table 2-1. See **Package Type** for the location of pins.

| Pin Number | Pin Name | Description  |
|------------|----------|--|
| 1          | INB      | Logic input  |
| 2          | VDD      | High-side supply voltage   |
| 3          | VSS      | Low-side supply voltage. VSS is also connected to the IC substrate. It is required to connect to the most negative potential of voltage supplies.  |
| 4          | INC      |  |
| 5          | IND      | Logic input  |
| 6          | GND      | Logic input ground reference   |
| 7          | VL       | Supply voltage for N-channel output stage  |
| 8          | OUTC     |  |
| 9          | OUTD     | Output drivers   |
| 10, 11     | VH       | Supply voltage for P-channel output stage  |
| 12         | OUTA     |  |
| 13         | OUTB     | Output drivers   |
| 14         | VL       | Supply voltage for N-channel output stage  |
| 15         | PE       | Power enable logic input. When PE is high, the input logic threshold is set. When PE is low, all outputs are at default state and the IC is in Standby mode. (See Table 1-1 and Figure 3-1.) |
| 16         | INA      | Logic input  |
| Subst      | trate    | The IC substrate is internally connected to the thermal pad. The thermal pad and VSS must be connected externally.   |

#### TABLE 2-1:PIN FUNCTION TABLE

### 3.0 APPLICATION INFORMATION

For proper operation of the MD1820, low-inductance bypass capacitors should be used on the various supply pins. The GND pin should be connected to the logic ground. The INA, INB, INC, IND and PE pins should be connected to a logic source with a swing of GND to PE, where PE is 1.8V to 5V. Good trace practices should be followed corresponding to the desired operating speed. The internal circuitry of the MD1820 is capable of operating up to 100 MHz, with the primary speed limitation being the loading effects of the load capacitance. Because of this speed and the high transient currents due to capacitive loads, the bypass capacitors should be as close to the chip pins as possible. Unless the load specifically requires bipolar drive, the  $V_{\rm SS}$  and  $V_{\rm L}$  pins should have a low-inductance bypass capacitor to GND and supply power connections. If these voltages are not zero, they need bypass capacitors similar to the positive power supplies. The power connection  $V_{\text{DD}}$  should have a ceramic bypass capacitor to the ground plane with short leads and decoupling components to prevent resonance in the powerleads.

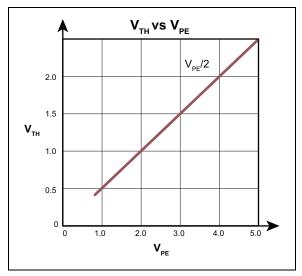
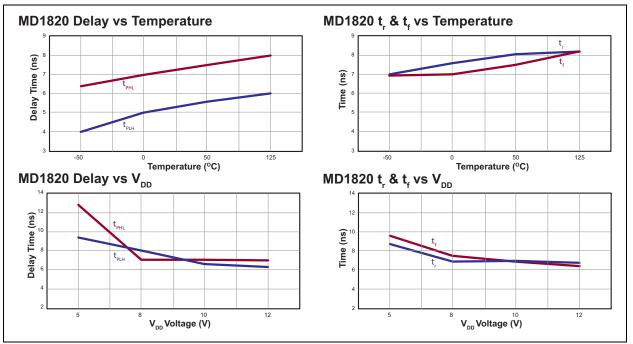


FIGURE 3-1: V<sub>TH</sub>/V<sub>PE</sub> Curve.





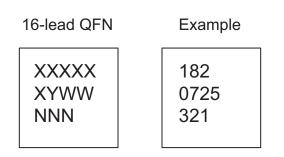
Timing Characteristics vs. Temperature and V<sub>DD</sub>.

The voltages of V<sub>H</sub> and V<sub>L</sub> decide the output signal levels. These two pins can draw fast transient currents of up to 2A, so they should be provided with an appropriate bypass capacitor located next to the chip pins. A ceramic capacitor of up to 1  $\mu$ F may be appropriate, with a series ferrite bead to prevent resonance in the power supply lead going to the capacitor. Pay particular attention to minimizing trace lengths, current loop area and using sufficient trace

width to reduce inductance. Surface-mount components are highly recommended. Since the output impedance of this driver is very low, in some cases, it may be desirable to add a small series resistor in series with the output signal to obtain better waveform transitions at the load terminals. This will reduce the output voltage slew rate at the terminals of a capacitive load. Make sure that parasitic couplings are minimized from the output to the input signal terminals. The parasitic feedback may cause oscillations or spurious waveform shapes on the edges of signal transitions. Since the input operates with signals down to 1.8V, even small coupled voltages may cause problems. The use of a solid ground plane and good power and signal layout practices will prevent this problem. Make sure that the circulating ground return current from a capacitive load will not react with common inductance to cause noise voltages in the input logic circuitry.

## 4.0 PACKAGING INFORMATION

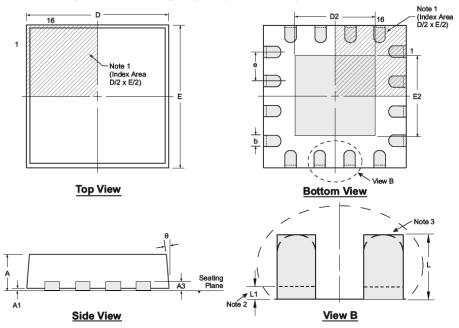
## 4.1 Package Marking Information



| Legend | : XXX<br>Y<br>YY<br>WW<br>NNN<br>@3<br>* | Product Code or Customer-specific information<br>Year code (last digit of calendar year)<br>Year code (last 2 digits of calendar year)<br>Week code (week of January 1 is week '01')<br>Alphanumeric traceability code<br>Pb-free JEDEC <sup>®</sup> designator for Matte Tin (Sn)<br>This package is Pb-free. The Pb-free JEDEC designator ((e3))<br>can be found on the outer packaging for this package. |
|--------|--|---|
|        | be carried<br>characters                 | nt the full Microchip part number cannot be marked on one line, it will<br>d over to the next line, thus limiting the number of available<br>s for product code or customer-specific information. Package may or<br>e the corporate logo.   |

# 16-Lead QFN Package Outline (K6)

3.00x3.00mm body, 1.00mm height (max), 0.50mm pitch



Note: For the most current package drawings, see the Microchip Packaging Specification at www.microchip.com/packaging.

Notes:

A Pin 1 identifier must be located in the index area indicated. The Pin 1 identifier can be: a molded mark/identifier; an embedded metal marker; or 1. a printed indicator.

Depending on the method of manufacturing, a maximum of 0.15mm pullback (L1) may be present. 2. 3.

The inner tip of the lead may be either rounded or square.

| Symb              | ol  | A    | A1   | A3          | b    | D     | D2   | E     | E2   | e           | L     | L1   | θ               |
|-------------------|-----|------|------|-------------|------|-------|------|-------|------|-------------|-------|------|-----------------|
|                   | MIN | 0.80 | 0.00 |             | 0.18 | 2.85* | 1.50 | 2.85* | 1.50 |             | 0.20† | 0.00 | <b>0</b> 0      |
| Dimension<br>(mm) | NOM | 0.90 | 0.02 | 0.20<br>REF | 0.25 | 3.00  | 1.65 | 3.00  | 1.65 | 0.50<br>BSC | 0.30† | -    | -               |
| ()                | MAX | 1.00 | 0.05 |             | 0.30 | 3.15* | 1.80 | 3.15* | 1.80 | 200         | 0.45  | 0.15 | 14 <sup>0</sup> |

JEDEC Registration MO-220, Variation VEED-4, Issue K, June 2006.

\* This dimension is not specified in the JEDEC drawing. † This dimension differs from the JEDEC drawing.

Drawings not to scale.

#### APPENDIX A: REVISION HISTORY

#### Revision A (May 2017)

- Converted Supertex Doc# DSFP-MD1820 to Microchip DS20005767A
- Changed the package marking format
- Changed the quantity of the K6 package from 3000/Reel to 3300/Reel
- Made minor text changes throughout the document

# **PRODUCT IDENTIFICATION SYSTEM**

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

|                   | Î Î  |  |  |  |  |  |
|-------------------|--|--|--|--|--|--|
| ackage<br>Options | Environmental Media Type   |  | MD1820K6-G:  | High-Speed 4-Channel MOSFET<br>Driver with Non-Inverting Outputs,<br>16-lead QFN, 3300/Reel  |  |  |
| D1820 =           | High-Speed 4-Channel MOSFET Driver<br>with Non-Inverting Outputs |  |  |  |  |  |
| 6 =               | 16-lead QFN  |  |  |  |  |  |
| -                 | Lead (Pb)-free/RoHS-compliant Package                            |  |  |  |  |  |
| lank) =           | 3300/Reel for a K6 Package                                       |  |  |  |  |  |
|                   |  |  |  |  |  |  |
|                   |  |  |  |  |  |  |
|                   |  |  |  |  |  |  |
| 0<br>6            | D1820 =<br>=<br>=  | ptions         D1820         =         High-Speed 4-Channel MOSFET Driver with Non-Inverting Outputs         =       16-lead QFN         =       Lead (Pb)-free/RoHS-compliant Package | a)<br>D1820 = High-Speed 4-Channel MOSFET Driver<br>with Non-Inverting Outputs<br>= 16-lead QFN<br>= Lead (Pb)-free/RoHS-compliant Package | a) MD1820K6-G:<br>a) MD1820K6-G:<br>a) MD1820K6-G:<br>a) MD1820K6-G:<br>a) MD1820K6-G:<br>a) MD1820K6-G:<br>a) MD1820K6-G:<br>b) for the formation of the fo |  |  |

#### Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE. Microchip disclaims all liability arising from this information and its use. Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights unless otherwise stated.

Microchip received ISO/TS-16949:2009 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company's quality system processes and procedures are for its PIC<sup>®</sup> MCUs and dsPIC<sup>®</sup> DSCs, KEELOQ<sup>®</sup> code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.

# QUALITY MANAGEMENT SYSTEM CERTIFIED BY DNV = ISO/TS 16949=

#### Trademarks

The Microchip name and logo, the Microchip logo, AnyRate, AVR, AVR logo, AVR Freaks, BeaconThings, BitCloud, CryptoMemory, CryptoRF, dsPIC, FlashFlex, flexPWR, Heldo, JukeBlox, KEELoa, KEELoa logo, Kleer, LANCheck, LINK MD, maXStylus, maXTouch, MediaLB, megaAVR, MOST, MOST logo, MPLAB, OptoLyzer, PIC, picoPower, PICSTART, PIC32 logo, Prochip Designer, QTouch, RightTouch, SAM-BA, SpyNIC, SST, SST Logo, SuperFlash, tinyAVR, UNI/O, and XMEGA are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

ClockWorks, The Embedded Control Solutions Company, EtherSynch, Hyper Speed Control, HyperLight Load, IntelliMOS, mTouch, Precision Edge, and Quiet-Wire are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Adjacent Key Suppression, AKS, Analog-for-the-Digital Age, Any Capacitor, AnyIn, AnyOut, BodyCom, chipKIT, chipKIT logo, CodeGuard, CryptoAuthentication, CryptoCompanion, CryptoController, dsPICDEM, dsPICDEM.net, Dynamic Average Matching, DAM, ECAN, EtherGREEN, In-Circuit Serial Programming, ICSP, Inter-Chip Connectivity, JitterBlocker, KleerNet, KleerNet logo, Mindi, MiWi, motorBench, MPASM, MPF, MPLAB Certified logo, MPLIB, MPLINK, MultiTRAK, NetDetach, Omniscient Code Generation, PICDEM, PICDEM.net, PICkit, PICtail, PureSilicon, QMatrix, RightTouch logo, REAL ICE, Ripple Blocker, SAM-ICE, Serial Quad I/O, SMART-I.S., SQI, SuperSwitcher, SuperSwitcher II, Total Endurance, TSHARC, USBCheck, VariSense, ViewSpan, WiperLock, Wireless DNA, and ZENA are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

Silicon Storage Technology is a registered trademark of Microchip Technology Inc. in other countries.

GestIC is a registered trademark of Microchip Technology Germany II GmbH & Co. KG, a subsidiary of Microchip Technology Inc., in other countries.

All other trademarks mentioned herein are property of their respective companies.

© 2017, Microchip Technology Incorporated, All Rights Reserved. ISBN: 978-1-5224-1748-4



# **Worldwide Sales and Service**

#### AMERICAS

Corporate Office 2355 West Chandler Blvd. Chandler, AZ 85224-6199 Tel: 480-792-7200 Fax: 480-792-7277 Technical Support: http://www.microchip.com/ support

Web Address: www.microchip.com

Atlanta Duluth, GA Tel: 678-957-9614 Fax: 678-957-1455

Austin, TX Tel: 512-257-3370

Boston Westborough, MA Tel: 774-760-0087 Fax: 774-760-0088

**Chicago** Itasca, IL Tel: 630-285-0071 Fax: 630-285-0075

**Dallas** Addison, TX Tel: 972-818-7423 Fax: 972-818-2924

Detroit Novi, MI Tel: 248-848-4000

Houston, TX Tel: 281-894-5983

Indianapolis Noblesville, IN Tel: 317-773-8323 Fax: 317-773-5453 Tel: 317-536-2380

Los Angeles Mission Viejo, CA Tel: 949-462-9523 Fax: 949-462-9608 Tel: 951-273-7800

Raleigh, NC Tel: 919-844-7510

New York, NY Tel: 631-435-6000

San Jose, CA Tel: 408-735-9110 Tel: 408-436-4270

**Canada - Toronto** Tel: 905-695-1980 Fax: 905-695-2078

#### ASIA/PACIFIC

Asia Pacific Office Suites 3707-14, 37th Floor Tower 6, The Gateway Harbour City, Kowloon

Hong Kong Tel: 852-2943-5100 Fax: 852-2401-3431

Australia - Sydney Tel: 61-2-9868-6733 Fax: 61-2-9868-6755

**China - Beijing** Tel: 86-10-8569-7000 Fax: 86-10-8528-2104

**China - Chengdu** Tel: 86-28-8665-5511 Fax: 86-28-8665-7889

China - Chongqing Tel: 86-23-8980-9588 Fax: 86-23-8980-9500

China - Dongguan Tel: 86-769-8702-9880

China - Guangzhou Tel: 86-20-8755-8029

**China - Hangzhou** Tel: 86-571-8792-8115 Fax: 86-571-8792-8116

China - Hong Kong SAR Tel: 852-2943-5100

**China - Nanjing** Tel: 86-25-8473-2460 Fax: 86-25-8473-2470

Fax: 852-2401-3431

**China - Qingdao** Tel: 86-532-8502-7355 Fax: 86-532-8502-7205

**China - Shanghai** Tel: 86-21-3326-8000 Fax: 86-21-3326-8021

China - Shenyang Tel: 86-24-2334-2829 Fax: 86-24-2334-2393

**China - Shenzhen** Tel: 86-755-8864-2200 Fax: 86-755-8203-1760

**China - Wuhan** Tel: 86-27-5980-5300 Fax: 86-27-5980-5118

**China - Xian** Tel: 86-29-8833-7252 Fax: 86-29-8833-7256 ASIA/PACIFIC

China - Xiamen Tel: 86-592-2388138 Fax: 86-592-2388130

China - Zhuhai Tel: 86-756-3210040 Fax: 86-756-3210049

India - Bangalore Tel: 91-80-3090-4444 Fax: 91-80-3090-4123

**India - New Delhi** Tel: 91-11-4160-8631 Fax: 91-11-4160-8632

India - Pune Tel: 91-20-3019-1500

Japan - Osaka Tel: 81-6-6152-7160 Fax: 81-6-6152-9310

**Japan - Tokyo** Tel: 81-3-6880- 3770 Fax: 81-3-6880-3771

**Korea - Daegu** Tel: 82-53-744-4301 Fax: 82-53-744-4302

Korea - Seoul Tel: 82-2-554-7200 Fax: 82-2-558-5932 or 82-2-558-5934

Malaysia - Kuala Lumpur Tel: 60-3-6201-9857 Fax: 60-3-6201-9859

Malaysia - Penang Tel: 60-4-227-8870 Fax: 60-4-227-4068

Philippines - Manila Tel: 63-2-634-9065 Fax: 63-2-634-9069

Singapore Tel: 65-6334-8870 Fax: 65-6334-8850

**Taiwan - Hsin Chu** Tel: 886-3-5778-366 Fax: 886-3-5770-955

Taiwan - Kaohsiung Tel: 886-7-213-7830

Taiwan - Taipei Tel: 886-2-2508-8600 Fax: 886-2-2508-0102

Thailand - Bangkok Tel: 66-2-694-1351 Fax: 66-2-694-1350

#### EUROPE

Austria - Wels Tel: 43-7242-2244-39 Fax: 43-7242-2244-393

**Denmark - Copenhagen** Tel: 45-4450-2828 Fax: 45-4485-2829

Finland - Espoo Tel: 358-9-4520-820

France - Paris Tel: 33-1-69-53-63-20 Fax: 33-1-69-30-90-79

France - Saint Cloud Tel: 33-1-30-60-70-00

**Germany - Garching** Tel: 49-8931-9700 **Germany - Haan** Tel: 49-2129-3766400

Germany - Heilbronn Tel: 49-7131-67-3636

Germany - Karlsruhe Tel: 49-721-625370

**Germany - Munich** Tel: 49-89-627-144-0 Fax: 49-89-627-144-44

**Germany - Rosenheim** Tel: 49-8031-354-560

Israel - Ra'anana Tel: 972-9-744-7705

Italy - Milan Tel: 39-0331-742611 Fax: 39-0331-466781

Italy - Padova Tel: 39-049-7625286

**Netherlands - Drunen** Tel: 31-416-690399 Fax: 31-416-690340

Norway - Trondheim Tel: 47-7289-7561

Poland - Warsaw Tel: 48-22-3325737

Romania - Bucharest Tel: 40-21-407-87-50

**Spain - Madrid** Tel: 34-91-708-08-90 Fax: 34-91-708-08-91

Sweden - Gothenberg Tel: 46-31-704-60-40

Sweden - Stockholm Tel: 46-8-5090-4654

**UK - Wokingham** Tel: 44-118-921-5800 Fax: 44-118-921-5820

# **Mouser Electronics**

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

Microchip:

MD1820K6-G